

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shigemi TOCHINO</td> <td>02/04/2013</td> </tr> <tr> <td>Hiroyoshi SAWA</td> <td>02/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	Shigemi TOCHINO	02/04/2013	Hiroyoshi SAWA	02/04/2013
Name	Execution Date						
Shigemi TOCHINO	02/04/2013						
Hiroyoshi SAWA	02/04/2013						
RECEIVING PARTY DATA							
Name:	HORIBA, Ltd.						
Street Address:	2, Miyano Higashi-cho						
Internal Address:	Kisshoin, Minami-ku, Kyoto-shi						
City:	Kyoto						
State/Country:	JAPAN						
Postal Code:	601-8510						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13768023</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13768023		
Property Type	Number						
Application Number:	13768023						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Daniel P. Lent						
Total Attachments: 2 source=6KX9875#page1.tif source=6KX9875#page2.tif							

OP \$40.00 13768023

ASSIGNMENT

WHEREAS We, **Shigemi TOCHINO** and **Hiroyoshi SAWA** of c/o **HORIBA, Ltd.**,
2, Miyanohigashi-cho, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8510, Japan
(hereinafter referred to as "ASSIGNORS") have invented certain new and useful
improvements in:

PARTICLE DIAMETER DISTRIBUTION MEASUREMENT DEVICE

which claims priority to Japanese Application No. 2012-032162, filed February 16, 2012,
and for which I am about to file or have filed an application for Letters Patent of the United
States;

AND WHEREAS, **HORIBA, Ltd.** (hereinafter referred to as "ASSIGNEE"), a
corporation organized and existing under the laws of the Country of **Japan** having a place of
business at **2, Miyanohigashi-cho, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8510,**
Japan is desirous of acquiring an interest in the United States and all foreign countries, in and
to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for
good and valuable consideration, the receipt of which is hereby acknowledged, We, the said
ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said
ASSIGNEE, the entire right, title and interest in and to said invention in the United States and
in all foreign countries, including priority rights, as fully set forth and described in said
application; and We do hereby authorize and request the Commissioner of Patents to issue said
Letters Patent on said application, and any and all Letters Patent that may be issued upon any
and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof,
to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for
the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that
the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will
execute all papers necessary in connection with the United States and foreign applications
when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will,

at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 4. Feb. 2013

Shigemi Tochino L.S.
Shigemi TOCHINO

Date: 4. Feb. 2013

Hiroyoshi Sawa L.S.
Hiroyoshi SAWA